

Title (en)  
LOW INDUCTANCE ENCAPSULATED PACKAGE INCLUDING A SEMICONDUCTOR CHIP.

Title (de)  
VERKAPSELTE PACKUNG NIEDRIGER INDUKTANZ MIT EINEM HALBLEITERCHIP.

Title (fr)  
MODULE ENCAPSULE A FAIBLE INDUCTANCE COMPRENANT UNE PUCE A SEMI-CONDUCTEUR.

Publication  
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Application  
**EP 90917818 A 19900612**

Priority  
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Abstract (en)  
[origin: WO9100617A1] A non-hermetic encapsulated semiconductor device package (90) includes wide flat leads (46b, 48b) bonded to the upper surface contact pads (16, 18) of the device. These leads are preferably solderless bonded to these contact pads.

Abstract (fr)  
Un module (90) à dispositif semi-conducteur encapsulé non hermétique comprend des sorties plates et larges (46b, 48b) liées aux pastilles de contact (16, 18) de la surface supérieure du dispositif. Ces sorties sont de préférence liées sans brasage à ces pastilles de contact.

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IPC 8 full level  
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Citation (search report)  
See references of WO 9100617A1

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